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Packaging of components for automatic handling – Part 5: Matrix trays

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –

Part 5: Matrix trays

FOREWORD

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International Standard IEC 60286-5 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This edition includes the following significant technical changes from the previous edition.

- a) The generic rules for the design of matrix trays are given in this standard. Newly developed trays which follow these rules will not be listed individually. Only those trays which conform to the design rules set forth herein are classified as "standard trays" and are thus preferred for use.
- b) An update of the matrix trays, which do not conform to the design rules set forth herein, are considered as "non-standard trays" and are not preferred for use, is listed in Annex A.

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This consolidated version of IEC 60286-5 consists of the second edition (2003) [documents 40/1341/FDIS and 40/1364/RVD] and its amendment 1 (2009) [documents 40/1942/FDIS and 40/1971/RVD].

The technical content is therefore identical to the base edition and its amendment and has been prepared for user convenience.

It bears the edition number 2.1.

A vertical line in the margin shows where the base publication has been modified by amendment 1.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of the base publication and its amendments will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –

Part 5: Matrix trays

1 Scope

This part of IEC 60286 describes the common dimensions, tolerances and characteristics of the tray. It includes only those dimensions which are essential for the handling of the trays for the stated purpose and for placing or removing components from the trays.

Matrix trays are designed to facilitate the transport and handling of electronic components during their testing, baking, transport/storage, and final mounting by automatic placement equipment.

The generic rules for their design are given in this standard.. Newly developed trays which follow these rules will not be listed individually . Only those trays which conform to the design rules set forth herein are classified as “standard trays” and are thus preferred for use.

NOTE Matrix trays listed in Annex A which do not conform to the design rules set forth herein shall be considered as “non-standard trays” and are not preferred for use.

2 Material

2.1 Electrostatic dissipative requirements

Trays shall be moulded from material that meets the ESD dissipative requirements with surface resistance equal to or greater than $1,0 \times 10^5$ ohms/square but less than $1,0 \times 10^{11}$ ohms/square.

2.2 Effect of properties

The tray material shall not adversely affect the mechanical, electrical characteristics, solderability, or marking of the component during or after transport, baking or storage in the tray.

2.3 Recycling and rigidity

The tray material shall be reusable or recyclable and shall be rigid enough to avoid damage to the components during handling, loading, baking, testing, shipping and placement operations.

There should be space for a recycle logo and material code or material declaration close to ‘Detail B’.

3 Mechanical stability

3.1 Loaded tray

Mechanical stability of loaded trays shall be such that the components are adequately retained, without lead damage, and can be easily removed from the tray.

3.2 Empty tray

The empty tray shall withstand normal environmental conditions (including component baking temperatures, if required) without distorting, warping, expanding, shrinking or any other physical change outside the specified dimensions of the trays.